

54AC16620, 74AC16620 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCAS239A – JULY 1990 – REVISED APRIL 1996

- **Members of the Texas Instruments Widebus™ Family**
- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise**
- **EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings**

description

The 'AC16620 are inverting 16-bit transceivers designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing.

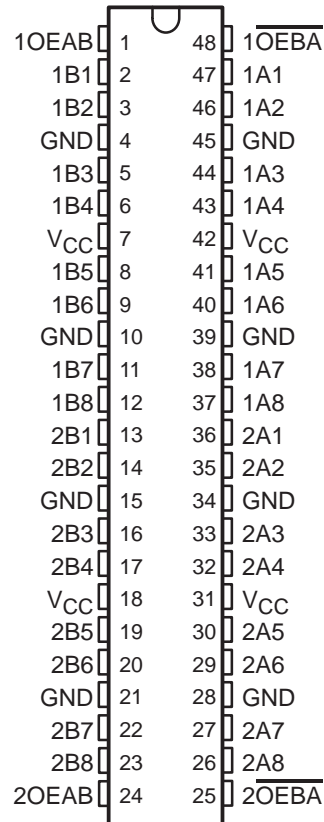
These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the complementary output-enable (OEAB or OEBA) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives the transceiver the capability to store data by simultaneously enabling OEAB and OEBA. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, the bus lines remain at their last states.

The 74AC16620 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16620 is characterized for operation over the full military temperature range of -55°C to 125°C. The 74AC16620 is characterized for operation from -40°C to 85°C.

54AC16620 . . . WD PACKAGE
74AC16620 . . . DL PACKAGE
(TOP VIEW)



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 **TEXAS
INSTRUMENTS**

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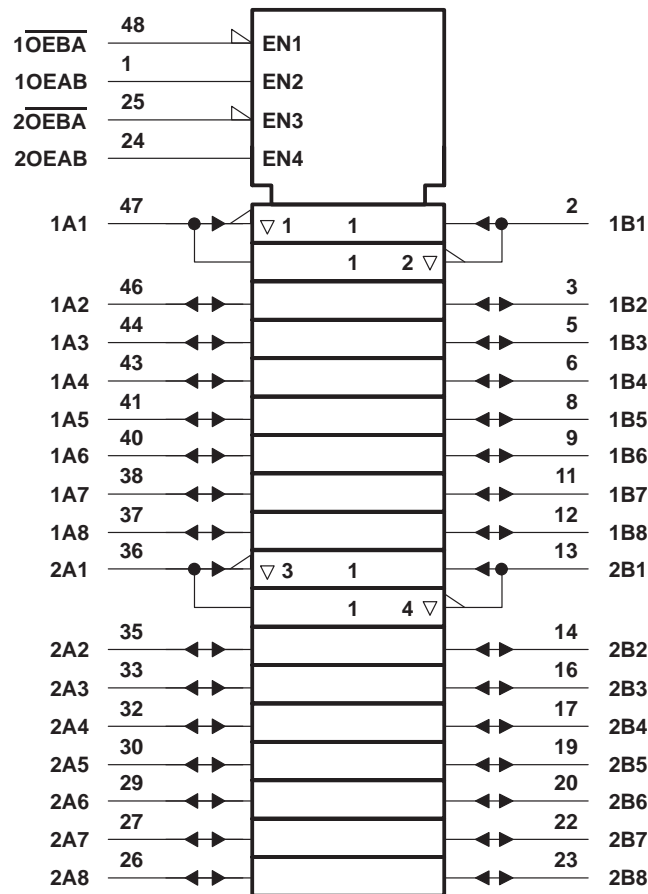
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FUNCTION TABLE
 (each 8-bit section)

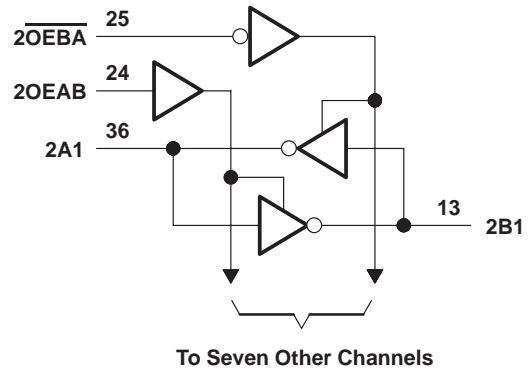
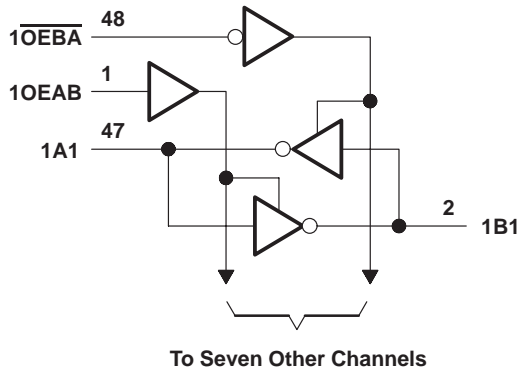
INPUTS		OPERATION
\overline{OEBA}	OEAB	
L	L	\overline{B} data to A bus
L	H	\overline{B} data to A bus, A data to B bus
H	L	Isolation
H	H	A data to B bus

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 50 mA
Continuous current through V_{CC} or GND	± 400 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T_{Stg}	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

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recommended operating conditions (see Note 2)

		54AC16620			74AC16620			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	3	5	5.5	3	5	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 3 V		2.1	2.1		V	
		V _{CC} = 4.5 V		3.15	3.15			
		V _{CC} = 5.5 V		3.85	3.85			
V _{IL}	Low-level input voltage	V _{CC} = 3 V			0.9	0.9	V	
		V _{CC} = 4.5 V			1.35	1.35		
		V _{CC} = 5.5 V			1.65	1.65		
V _I	Input voltage	0		V _{CC}	0	V _{CC}	V	
V _O	Output voltage	0		V _{CC}	0	V _{CC}	V	
I _{OH}	High-level output current	V _{CC} = 3 V			-4	-4	mA	
		V _{CC} = 4.5 V			-24	-24		
		V _{CC} = 5.5 V			-24	-24		
I _{OL}	Low-level output current	V _{CC} = 3 V			12	12	mA	
		V _{CC} = 4.5 V			24	24		
		V _{CC} = 5.5 V			24	24		
Δt/Δv	Input transition rise or fall rate	0		10	0	10	ns/V	
T _A	Operating free-air temperature	-55		125	-40	85	°C	

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			54AC16620		74AC16620		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	3 V	2.9			2.9	2.9	V		
		4.5 V	4.4			4.4	4.4			
		5.5 V	5.4			5.4	5.4			
	I _{OH} = -4 mA	3 V	2.58			2.48	2.48			
		4.5 V	3.94			3.8	3.8			
		5.5 V	4.94			4.8	4.8			
I _{OH} = -75 mA†	5.5 V				3.85	3.85				
V _{OL}	I _{OL} = 50 μA	3 V		0.1		0.1	0.1	V		
		4.5 V		0.1		0.1	0.1			
		5.5 V		0.1		0.1	0.1			
	I _{OL} = 12 mA	3 V		0.36		0.44	0.44			
		4.5 V		0.36		0.44	0.44			
		5.5 V		0.36		0.44	0.44			
I _{OL} = 75 mA†	5.5 V				1.65	1.65				
I _I	Control inputs	V _I = V _{CC} or GND	5.5 V		±0.1	±1	±1	μA		
I _{OZ} ‡	A or B ports	V _O = V _{CC} or GND	5.5 V		±0.5	±5	±5	μA		
I _{CC}		V _I = V _{CC} or GND, I _O = 0	5.5 V		8	80	80	μA		
C _i	Control inputs	V _I = V _{CC} or GND	5 V		4.5			pF		
C _{io}	A or B ports	V _O = V _{CC} or GND	5 V		16			pF		

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			54AC16620		74AC16620		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	2.7	6.1	8.7	2.7	9.7	2.7	9.7	ns
t_{PHL}			3.9	7.9	10.6	3.9	11.7	3.9	11.7	
t_{PZH}	$\overline{\text{OEBA}}$	A	3.2	7.1	10	3.2	11.2	3.2	11.2	ns
t_{PZL}			4.5	11.1	13.5	4.5	15	4.5	15	
t_{PHZ}	$\overline{\text{OEBA}}$	A	5.3	7.4	9.5	5.3	10.2	5.3	10.2	ns
t_{PLZ}			4.6	7	9.2	4.6	9.8	4.6	9.8	
t_{PZH}	OEAB	B	3.1	6.7	9.5	3.1	10.7	3.1	10.7	ns
t_{PZL}			4.4	9.6	13	4.4	14.5	4.4	14.5	
t_{PHZ}	OEAB	B	5	7.1	9.3	5	9.8	5	9.8	ns
t_{PLZ}			4.4	6.8	8.9	4.4	9.4	4.4	9.4	

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			54AC16620		74AC16620		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	2.1	3.9	6.1	2.1	6.8	2.1	6.8	ns
t_{PHL}			3.1	4.9	7.3	3.1	8.2	3.1	8.2	
t_{PZH}	$\overline{\text{OEBA}}$	A	2.2	4.3	6.8	2.2	7.6	2.2	7.6	ns
t_{PZL}			3.3	5.5	8.4	3.3	9.4	3.3	9.4	
t_{PHZ}	$\overline{\text{OEBA}}$	A	4.9	6.6	8.6	4.9	9.2	4.9	9.2	ns
t_{PLZ}			4.1	5.8	7.8	4.1	8.3	4.1	8.3	
t_{PZH}	OEAB	B	2.2	4.2	6.5	2.2	7.3	2.2	7.3	ns
t_{PZL}			3.4	5.4	8.1	3.4	9.1	3.4	9.1	
t_{PHZ}	OEAB	B	4.6	6.4	8.5	4.6	9	4.6	9	ns
t_{PLZ}			4.1	5.6	7.6	4.1	8	4.1	8	

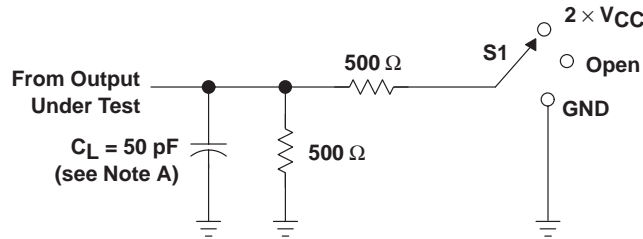
operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	$C_L = 50\text{ pF}$, $f = 1\text{ MHz}$	49	pF
		Outputs disabled		6	

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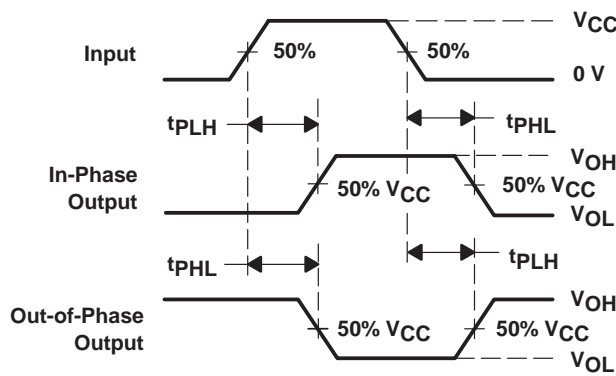
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PARAMETER MEASUREMENT INFORMATION

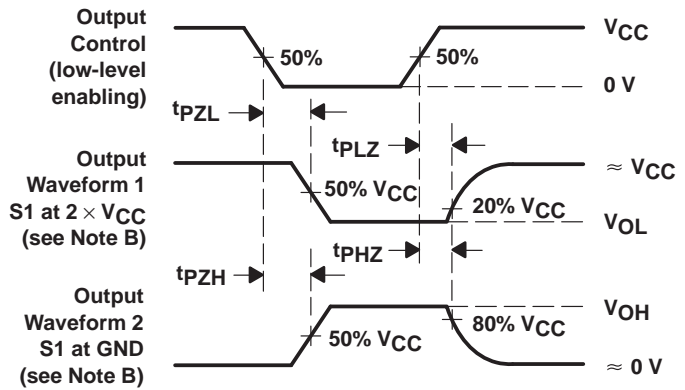


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 3$ ns, $t_f = 3$ ns.
 D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AC16620DL	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI
74AC16620DLR	OBSOLETE	SSOP	DL	48		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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